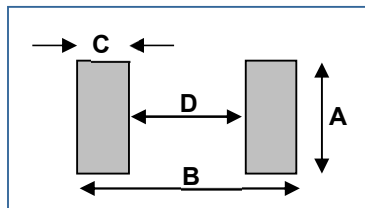


Technical Note TN006: Recommended Layouts for SMD Resistors



The following nominal dimensions are recommended for reflow solder processing:

Reflow Solder Pad Dimensions (mm)				
Type & Size	A	B	C	D
Chip 0402	0.65	1.30	0.45	0.40
Chip 0603	1.00	2.10	0.70	0.70
Chip 0805	1.50	2.60	0.85	0.90
Chip 1206	2.00	4.00	1.25	1.50
Chip 2010	3.05	6.50	1.50	3.50
Chip 2512	3.70	7.75	1.50	4.75
MELF 0102	1.40	2.85	1.10	0.65
MELF 0204	1.75	4.00	1.25	1.50
MELF 0207	2.20	7.20	2.20	2.80

The following nominal dimensions are recommended for wave solder processing:

Wave Solder Pad Dimensions (mm)				
Type & Size	A	B	C	D
Chip 0402	0.75	1.50	0.55	0.40
Chip 0603	1.10	2.30	0.80	0.70
Chip 0805	1.60	3.00	1.05	0.90
Chip 1206	2.10	4.40	1.45	1.50
Chip 2010	3.15	7.70	1.70	4.30
Chip 2512	3.80	8.35	1.70	4.95
MELF 0102	1.50	3.45	1.40	0.65
MELF 0204	1.90	4.70	1.60	1.50
MELF 0207	2.50	7.40	2.30	2.80